

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A resin encapsulating method for a semiconductor chip comprising adhering a pressure-sensitive adhesive tape to a leadframe, bonding a semiconductor chip to a the leadframe having the pressure-sensitive adhesive tape adhered thereto, encapsulating the semiconductor chip with a resin in a mold, and stripping the pressure-sensitive adhesive tape, wherein the pressure-sensitive adhesive tape has a thermal shrinkage of 3% or less on resin encapsulating and a pressure-sensitive adhesive strength of 400gf/20 mm or less at 23°C after the adhesive tape being heated at 180°C.

2. (currently amended): A resin encapsulating method for a semiconductor chip comprising adhering a pressure-sensitive adhesive tape to a tape carrier film, bonding a semiconductor chip to the tape carrier film having the pressure-sensitive adhesive tape adhered thereto, encapsulating the semiconductor chip with a resin and a mold, and stripping the pressure-sensitive adhesive tape, wherein the pressure-sensitive adhesive tape has a thermal shrinkage of 3% or less on resin encapsulating and a pressure-sensitive adhesive strength of 400gf/20 mm or less at 23°C after the adhesive tape being heated at 180°C.

Claims 3-5. (canceled).